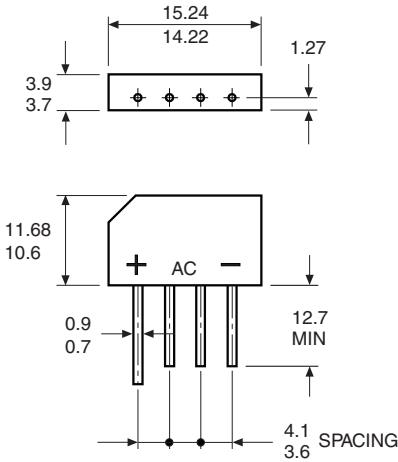


1.5 Amp. Glass Passivated Bridge Rectifiers

Dimensions in mm.	KBP	Voltage 400 V to 1000 V	Current 1.5 A
 Top View Dimensions: 15.24, 14.22, 1.27, 3.9, 3.7 Side View Dimensions: 11.68, 10.6, 0.9, 0.7, 12.7 MIN, 4.1, 3.6 SPACING		• Glass passivated chip junction • Ideal for printed circuit board • Reliable low cost construction • High temperature soldering guaranteed: 260 °C / 10 seconds at 5 lbs., (2.3 Kg), tension.	
		MECHANICAL DATA • Case: Molded plastic body. • Mounting position: Any • Leads solderable per MIL-STD-202, Method 208	

Maximum Ratings and Electrical Characteristics at 25 °C

		KBP 154G	KBP 155G	KBP 156G	KBP 157G
V_{RRM}	Maximum Recurrent Peak Reverse Voltage (V)	400	600	800	1000
V_{RMS}	Maximum RMS Voltage (V)	280	420	560	700
V_{DC}	Maximum DC Blocking Voltage (V)	400	600	800	1000
$I_{F(AV)}$	Maximum Average Forward Rectified Current @ $T_A = 50\text{ °C}$	1.5 A			
I_{FSM}	Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)	50 A			
T_j	Operating Temperature Range	-55 to +150 °C			
T_{stg}	Storage Temperature Range	-55 to +150 °C			

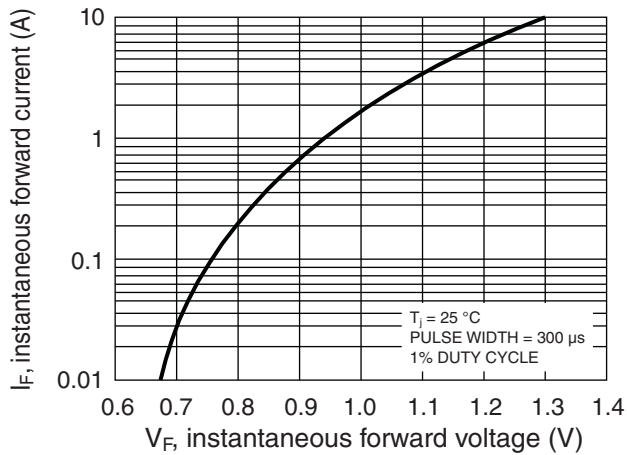
Electrical Characteristics at $T_{amb} = 25\text{ °C}$

V_F	Maximum Instantaneous Forward Voltage @ = 1.5 A	1.1 V
I_R	Maximum DC Reverse Current @ $T_A = 25\text{ °C}$ at Rated DC Blocking Voltage @ $T_A = 125\text{ °C}$	10.0 μ A 500 μ A
$R_{th(j-a)}$	Typical Thermal Resistance (Note)	40 °C/W
$R_{th(j-l)}$		13 °C/W

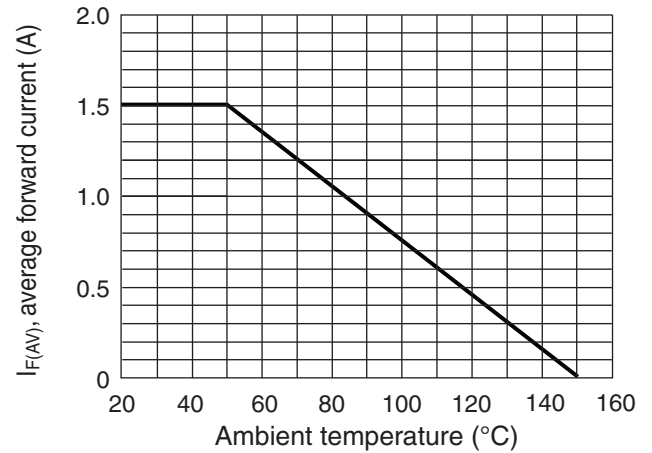
Note: Thermal Resistance from Junction to Ambient and from Junction to Lead Mounted on P.C.B. with 0.4" x 0.4" (10 mm x 10 mm) Copper Pads.

Rating And Characteristic Curves

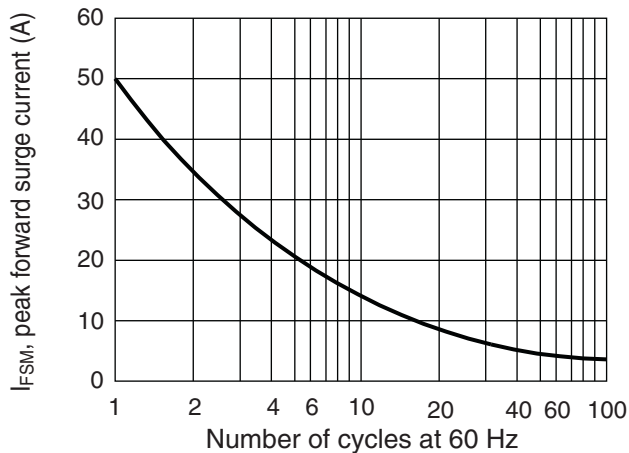
TYPICAL FORWARD CHARACTERISTICS
PER BRIDGE ELEMENT



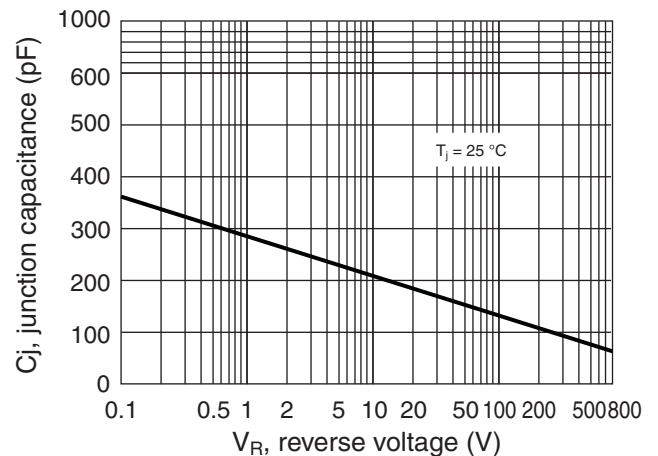
MAXIMUM FORWARD CURRENT DERATING
CURVE



MAXIMUM NON-REPETITIVE FORWARD
SURGE CURRENT PER BRIDGE ELEMENT



TYPICAL JUNCTION CAPACITANCE



TYPICAL REVERSE CHARACTERISTICS

